


TSMC2007.0842/1085.538

<b>RECORDATION FORM COVER SHEET</b> <b>PATENTS ONLY</b>		U.S. DEPARTMENT OF COMMERCE U.S. Patent and Trademark Office
Form PTO-1595 (Rev. 03/01) OMB No. 0651-0027 (exp. 5/31/2002) Tab settings ⇌ ⇌ ⇌		
To the Honorable Commissioner of Patents and Trademarks: Please record the attached original documents or copy thereof.		
<b>1. Name of conveying party(ies):</b> Hsiang-Huan Lee Ming Han Lee Ming-Shih Yeh Chen-Hua Yu Additional name(s) of conveying party(ies) attached? <input type="checkbox"/> Yes <input checked="" type="checkbox"/> No	<b>2. Name and address of receiving party(ies)</b> Name: <u>Taiwan Semiconductor Manufacturing Co., Ltd.</u> Internal Address: _____ _____ _____ Street Address: <u>No. 8, Li-Hsin Road 6</u> <u>Science Based Industrial Park</u> City: <u>Hsin-Chu</u> State: _____ Zip: _____ Country: <u>Taiwan 300-77 R.O.C.</u> Additional name(s) & address(es) attached? <input type="checkbox"/> Yes <input checked="" type="checkbox"/> No	
<b>3. Nature of conveyance:</b> <input checked="" type="checkbox"/> Assignment <input type="checkbox"/> Merger <input type="checkbox"/> Security Agreement <input type="checkbox"/> Change of Name <input type="checkbox"/> Other _____ Execution Date: <u>04/17/2008</u>		
<b>4. Application number(s) or patent number(s):</b> If this document is being filed together with a new application, the execution date of the application is: _____ A. Patent Application No.(s) <u>12/112,405</u> _____ B. Patent No.(s) _____ _____ Additional numbers attached? <input type="checkbox"/> Yes <input checked="" type="checkbox"/> No		
<b>5. Name and address of party to whom correspondence concerning document should be mailed:</b> Name: <u>Steven E. Koffs, Esquire</u> Internal Address: <u>Duane Morris LLP</u> _____ _____ Street Address: <u>30 South 17th Street</u> _____ City: <u>Philadelphia</u> State: <u>PA</u> Zip: <u>19103-4196</u>	<b>6. Total number of applications and patents involved:</b> <u>1</u> <b>7. Total fee (37 CFR 3.41).....\$ 40.00</b> <input type="checkbox"/> Enclosed <input type="checkbox"/> Authorized to be charged to deposit account <u>Already charged on 5/30/2008</u> <b>8. Deposit account number:</b> <u>04-1679</u>	
<b>DO NOT USE THIS SPACE</b>		
<b>9. Signature.</b> <div style="display: flex; justify-content: space-between; align-items: flex-end; margin-top: 20px;"> <div style="text-align: center;"> <u>Joseph A. Powers, Esquire</u>            Name of Person Signing         </div> <div style="text-align: center;">             Signature         </div> <div style="text-align: center;"> <u>06/04/2008</u>            Date         </div> </div> <div style="text-align: right; margin-top: 10px;">           Total number of pages including cover sheet, attachments, and documents: <u>12</u> </div>		

Mail documents to be recorded with required cover sheet information to:  
 Commissioner of Patents & Trademarks, Box Assignments  
 Washington, D.C. 20231

Serial No. 12/112,405  
Filed: 04/30/2008

ATTORNEY DOCKET NO.: 2007.0842/1085.538

### ASSIGNMENT AND AGREEMENT

For value received, we, Hsiang-Huan Lee, Ming Han Lee, Ming-Shih Yeh, and Chen-Hua Yu hereby sell, assign and transfer to Taiwan Semiconductor Manufacturing Co., Ltd. with its principal place of business located at No. 8, Li-Hsin Road 6, Science-Based Industrial Park, Hsin-Chu, Taiwan 300-77, Republic of China, and its successors, assigns and legal representatives, the entire right, title and interest, for the United States of America, in and to certain inventions related to **LOW RESISTANCE HIGH RELIABILITY CONTACT VIA AND METAL LINE STRUCTURE FOR SEMICONDUCTOR DEVICE** described in Provisional Application Serial 61/067,698 filed February 29, 2008 and a non-provisional application for Letters Patent of the United States and all the rights and privileges in said applications, and under any and all Letters Patent and any divisions, continuations, continuations-in-part, reexamination certificates, reissues, and extensions thereof, or claiming priority therefrom that may be granted in the United States for said inventions; and we also concurrently hereby sell, assign and transfer to Taiwan Semiconductor Manufacturing Co., Ltd. the entire right, title and interest in and to said inventions for all countries foreign to the United States, including all rights of priority arising from the application aforesaid, and all the rights and privileges under any and all forms of protection, including Letters Patent, that may be granted in said countries foreign to the United States for said inventions.

We authorize Taiwan Semiconductor Manufacturing Co., Ltd. to make application for such protection in its own name and maintain such protection in any and all countries foreign to the United States, and to invoke and claim for any application for patent or other form of protection for said inventions, without further authorization from us, any and all benefits, including the right of priority provided by any and all treaties, conventions, or agreements.

We hereby consent that a copy of this assignment shall be deemed a full legal and formal equivalent of any document which may be required in any country in proof of the right of Taiwan Semiconductor Manufacturing Co., Ltd. to apply for patent or other form of protection for said inventions and to claim the aforesaid benefit of the right of priority.

We request that any and all patents for said inventions be issued to Taiwan Semiconductor Manufacturing Co., Ltd. in the United States and in all countries foreign to the United States, or to such nominees as Taiwan Semiconductor Manufacturing Co., Ltd. may designate.

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ATTORNEY DOCKET NO.: 2007.0842/1085.538

We agree that, when requested, we shall, without charge to Taiwan Semiconductor Manufacturing Co., Ltd. but at its expense, sign all papers, and do all acts which may be necessary, desirable or convenient in connection with said applications, patents, or other forms of protection.

Inventor No. 1

Dated: 4/17, 2008Hsiang-Huan Lee  
Hsiang-Huan Lee

Residence:

No. 12, Alley 46, Lane 315, Syuefu E. Road, Jhudong Township, Hsinchu County 310,  
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Inventor No. 2

Dated: 4/17, 2008Ming Han Lee  
Ming Han Lee

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Inventor No. 3

Dated: 4/17, 2008Ming-Shih Yeh  
Ming-Shih Yeh

Residence:

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Inventor No. 4

Dated: 4/17/08Chen-Hua Yu  
Chen-Hua Yu

Residence:

No. 3, 38 Waterfront Road 2, Hsin-Chu, Taiwan, R.O.C.

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6/2/2008 5:39:36 AM PAGE 3/006 Fax Server

TO: STEVEN E. KOFFS, DUANE MORRIS LLP COMPANY: 30 SOUTH 17TH STREET

## PATENT ASSIGNMENT

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SUBMISSION TYPE:	NEW ASSIGNMENT												
NATURE OF CONVEYANCE:	ASSIGNMENT												
CONVEYING PARTY DATA													
<table border="1"><thead><tr><th>Name</th><th>Execution Date</th></tr></thead><tbody><tr><td>Hsiang-Huan Lee</td><td>04/17/2008</td></tr><tr><td>Ming Han Lee</td><td>04/17/2008</td></tr><tr><td>Ming-Shih Yeh</td><td>04/17/2008</td></tr><tr><td>Chen-Hua Yu</td><td>04/17/2008</td></tr></tbody></table>		Name	Execution Date	Hsiang-Huan Lee	04/17/2008	Ming Han Lee	04/17/2008	Ming-Shih Yeh	04/17/2008	Chen-Hua Yu	04/17/2008		
Name	Execution Date												
Hsiang-Huan Lee	04/17/2008												
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Ming-Shih Yeh	04/17/2008												
Chen-Hua Yu	04/17/2008												
RECEIVING PARTY DATA													
<table border="1"><tr><td>Name:</td><td>Taiwan Semiconductor Manufacturing Co., Ltd.</td></tr><tr><td>Street Address:</td><td>No. 8, Li-Hsin Road 6</td></tr><tr><td>Internal Address:</td><td>Science-Based Industrial Park</td></tr><tr><td>City:</td><td>Hsin-Chu</td></tr><tr><td>State/Country:</td><td>TAIWAN</td></tr><tr><td>Postal Code:</td><td>300-77</td></tr></table>		Name:	Taiwan Semiconductor Manufacturing Co., Ltd.	Street Address:	No. 8, Li-Hsin Road 6	Internal Address:	Science-Based Industrial Park	City:	Hsin-Chu	State/Country:	TAIWAN	Postal Code:	300-77
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PROPERTY NUMBERS Total: 1													
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CORRESPONDENCE DATA													
Fax Number: (215)979-1020 <i>Correspondence will be sent via US Mail when the fax attempt is unsuccessful.</i>													
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ATTORNEY DOCKET NUMBER:	N1085-00538												
NAME OF SUBMITTER:	Steven E. Koffs												

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Total Attachments: 2

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Serial No. 12/112,405  
Filed: 04/30/2008

ATTORNEY DOCKET NO.: 2007.0642/1085.538

**ASSIGNMENT AND AGREEMENT**

For value received, we, Hsiang-Huan Lee, Ming Han Lee, Ming-Shih Yeh, and Chen-Hua Yu hereby sell, assign and transfer to Taiwan Semiconductor Manufacturing Co., Ltd., with its principal place of business located at No. 8, Li-Hsin Road 6, Science-Based Industrial Park, Hsin-Chu, Taiwan 300-77, Republic of China, and its successors, assigns and legal representatives, the entire right, title and interest, for the United States of America, in and to certain inventions related to **LOW RESISTANCE HIGH RELIABILITY CONTACT VIA AND METAL LINE STRUCTURE FOR SEMICONDUCTOR DEVICE** described in Provisional Application Serial 61/067,698 filed February 29, 2008 and a non-provisional application for Letters Patent of the United States and all the rights and privileges in said applications, and under any and all Letters Patent and any divisions, continuations, continuations-in-part, reexamination certificates, reissues, and extensions thereof, or claiming priority therefrom that may be granted in the United States for said inventions; and we also concurrently hereby sell, assign and transfer to Taiwan Semiconductor Manufacturing Co., Ltd. the entire right, title and interest in and to said inventions for all countries foreign to the United States, including all rights of priority arising from the application aforesaid, and all the rights and privileges under any and all forms of protection, including Letters Patent, that may be granted in said countries foreign to the United States for said inventions.

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TO: STEVEN E. KOFFS, DUANE MORRIS LLP COMPANY: 30 SOUTH 17TH STREET

Sheng Sheng Electronics Co., Ltd.

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Dated: 4/17, 2008Ming-Shih Yeh  
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